

(Michael J. Doherty)

**EXPEDITED PROCEDURE**

Group Art Unit: 3729

Docket No.:

TESSERA 3.0-115 CONT CIP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Fjelstad et al.

Application No.: 09/766,814

Filed: January 22, 2001

For: MICROELECTRONIC PACKAGES HAVING  
DEFORMED BONDED LEADS AND  
METHODS THEREFOR

AMENDMENT UNDER 37 CFR 1.116

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The present Amendment is in response to the Final Office Action mailed April 20, 2004.

O.K. to Enter  
not 8/25/04